

C1210X309CATACTU

Aliases (C1210X309CATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 3 pF, +/-0.25 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

3 pF

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

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В	0.6mm +/-0.25mm
Packaging Specifications	

Packaging

3.3mm +/-0.4mm	Measurement Condition	1 MHz 1.0Vrms
2.6mm +/-0.3mm	Tolerance	+/-0.25 pF
0.78mm +/-0.20mm	Voltage DC	250 VDC
1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
0.6mm +/-0.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
4000	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

Specifications

Capacitance

Packaging Quantity	4000	Dissipation Factor	0
		Aging Rate	O T

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